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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
09/764,242	01/19/2001	George Wong	CS98-070B	8930
28112 75	01/23/2004		EXAMINER	
GEORGE O. SAILE & ASSOCIATES 28 DAVIS AVENUE			DIAZ, JOSE R	
	SIE, NY 12603		ART UNIT	PAPER NUMBER
			2815	

DATE MAILED: 01/23/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

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		Applicati	ion No.	Applicant(s)	
		09/764,2	.42	WONG, GEORGE	
	Office Action Summary	Examine	r	Art Unit	
		José R D	íaz	2815	
Period fo	The MAILING DATE of this commu or Reply	ınication appears on th	e cover sheet w	ith the correspondence address	
THE - External control	IORTENED STATUTORY PERIOD MAILING DATE OF THIS COMMUI ensions of time may be available under the provision of the state of this cone is period for reply specified above, the maximum ure to reply within the set or extended period for repreply received by the Office later than three months ed patent term adjustment. See 37 CFR 1.704(b).	NICATION. ns of 37 CFR 1.136(a). In no extended in the state of the s	vent, however, may a atutory minimum of thi will expire SIX (6) MO plication to become A	reply be timely filed rty (30) days will be considered timely. NTHS from the mailing date of this communication. BANDONED (35 U.S.C. § 133).	
1)⊠	Responsive to communication(s) fi	iled on <u>12 December 2</u>	<u>2003</u> .		
2a) <u></u>	This action is FINAL .	2b)⊠ This action is n	ion-final.		
3)	Since this application is in condition closed in accordance with the practice.	on for allowance excep ctice under <i>Ex parte</i> Q	t for formal ma uayle, 1935 C.l	ters, prosecution as to the merits is D. 11, 453 O.G. 213.	
Disposit	tion of Claims				
4)🖂	Claim(s) 18-22 is/are pending in the	ne application.			
	4a) Of the above claim(s) is.	/are withdrawn from co	onsideration.		
-	Claim(s) is/are allowed.				
•	Claim(s) <u>18-22</u> is/are rejected.				
-	Claim(s) is/are objected to.	riation and/or alastian	roquiromont		
,	Claim(s) are subject to rest	liction and/or election	requirement.		
	tion Papers				
	The specification is objected to by		.\□ abiaatad t	by the Everiner	
10)∟	The drawing(s) filed on is/ar				
	Applicant may not request that any ob			g(s) is objected to. See 37 CFR 1.121(d).	
11)	The oath or declaration is objected				
	under 35 U.S.C. §§ 119 and 120				
12)	Acknowledgment is made of a clai ☐ All b) Some * c) None of	f:		§ 119(a)-(d) or (f).	
•	1. Certified copies of the priori	ty documents have be	en received.	Application No.	
	2. Certified copies of the priori3. Copies of the certified copie	ty documents nave be	en received in nents have bee	n received in this National Stage	
	application from the Internal	tional Bureau (PCT Ru	ule 17.2(a)).		
*	See the attached detailed Office ac	tion for a list of the cer	tified copies no	t received.	n)
	since a specific reference was includ 37 CFR 1.78.	ded in the first sentend	ce of the specifi	 § 119(e) (to a provisional application cation or in an Application Data Shee 	et.
	a) 🔲 The translation of the foreign l				
14)⊠	Acknowledgment is made of a clain reference was included in the first so	n for domestic priority entence of the specific	under 35 U.S.C ation or in an A	c. §§ 120 and/or 121 since a specific application Data Sheet. 37 CFR 1.78.	
Attachme	nt(s)				
1) 🛛 Not	ice of References Cited (PTO-892)			Summary (PTO-413) Paper No(s)	
. =	ice of Draftsperson's Patent Drawing Review ormation Disclosure Statement(s) (PTO-1449		5) Notice of 6) Other:	Informal Patent Application (PTO-152)	

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DETAILED ACTION

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

- (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 1. Claims 18-19, 21 and 22 are rejected under 35 U.S.C. 103(a) as being unpatentable over Cheng (US Pat. No. 6,171,976 B1) in view of Applicant's admitted prior art.

Regarding claim 18, Cheng teaches a semiconductor substrate (see fig. 6) comprised of:

- (a) a patterned conductive layer (see col. 2, lines 64-67) forming portion of semiconductor devices (210) and patterned fill layer (212) in said kerf areas (204) (see fig. 6);
- (b) a spin-on-glass layer (220) over said patterned conductive layer (210, 212) converted to a planar silicon oxide layer (see col. 3, lines 29-31);
 - (c) an insulating layer (216) on said silicon oxide layer (220) (see fig. 6).

In addition, Cheng teaches that the disclosed invention is usable for VLSI and even for ULSI process (see col. 1, lines 19-20).

However, Cheng is silent with respect to the teaching of forming a multilevel of metal layers. Applicant acknowledged ULSI circuits requires more levels of metal to

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effectively interconnect the high density of discrete devices on the chip (see last paragraph of page 1, and lines 1-8 of page 2).

Cheng and Applicant's admitted prior art are analogous art because they are from the same field of endeavor as applicant's invention. At the time of the invention it would have been obvious to a person of ordinary skill in the art to provide additional levels of patterned conductive layer. The motivation for doing so, as is taught by Applicant, is effectively interconnecting the high density of discrete devices on the chip (page 2, lines 2-5). Therefore, it would have been obvious to combine Applicant's admitted prior art with Cheng to obtain the invention of claims 18-19 and 21-22.

Regarding claim 19, Cheng teaches that the conductive layer is a metal (see col. 4, lines 39-40).

Regarding claim 21, Cheng does not teach the limitation of wherein spacing between the patterned fill layers and the die areas in the range is not greater than about 2 μ m. However, it would have been obvious to one of ordinary skill in the art to include the claimed spacing range, since it has been held that where the general conditions of a claim are disclosed in the prior art, discovering the optimum or working ranges involves only routine skill in the art. In re Aller, 105 USPQ 233. The ordinary artisan would have been motivated to modify Cheng in the manner described above for at least the purpose of improving the uniformity of the chemical mechanical polishing process and avoiding the dishing effect (col. 2, lines 9-11 of Cheng).

Regarding claim 22, Cheng teaches that the kerf areas have a width of between about 120-600 µm between said die (see col. 2, lines 58-59).

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2. Claim 20 is rejected under 35 U.S.C. 103(a) as being unpatentable over Cheng (US Pat. No. 6,171,976 B1) in view of Applicant's admitted prior art, and further in view of Lou (US Patent No. 5,759,906).

Regarding claim 20, Cheng teaches that the patterned fill layer (212) and the device layer (210) are formed from the same material (see col. 2, lines 64-67).

However, Cheng is silent with respect to the metal material used to form said patterned conducting layer. Lou teaches that it is well known in the art to form an aluminum of about 6000 Å as the patterned conducting layer in the areas in which integrated circuits will be formed (see col. 5, lines 34-39 and Figs. 3-11).

Cheng, Applicant's admitted prior art and Lou are analogous art because they are from the same field of endeavor as applicant's invention. At the time of the invention it would have been obvious to a person of ordinary skill in the art to include a patterned conducting layer of aluminum having a thickness of about 6000 Å. The motivation for doing so, as is taught by Lou, is to provide a high electrical conductivity (col. 5, lines 33-34). Therefore, it would have been obvious to combine Lou with Cheng and Applicant's admitted prior art to obtain the invention of claim 20.

Response to Arguments

3. Applicant's arguments, filed December 12, 2003, with respect to the rejections of claims 18-22 have been fully considered and are persuasive. Therefore, the rejection has been withdrawn. However, upon further consideration, a new ground(s) of rejection is made in view of Cheng (US Pat. No. 6,171,976 B1).

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Conclusion

4. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Beilstein, Jr. et al. (US Pat. No. 5,804,464) discloses a conductive material formed in a kerf area (fig. 1), and Cronin et al. (US Pat. No. 5,691,248) discloses filled kerf area (37) (see abstract).

Correspondence

5. Any inquiry concerning this communication or earlier communications from the examiner should be directed to José R Díaz whose telephone number is (703) 308-6078 or (571) 272-1727, after February 9, 2004. The examiner can normally be reached on 9:00-5:00 Monday through Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Tom Thomas can be reached on (703) 308-2772. The fax phone number for the organization where this application or proceeding is assigned is (703) 308-7722.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

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